Product/Process Change Notice - PCN 19_0091 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Moisture Sensitivity Level Rating Change for HMC487
Publication Date:	16-May-2019
Effectivity Date:	16-May-2019 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:
Initial Release.

Description Of Change:

Moisture Sensitivity Level (MSL) rating is being changed from MSL1 to MSL3 for HMC487.

Reason For Change:

The MSL rating is being changed due to package-die interaction.

Impact of the change (positive or negative) on fit, form, function & reliability:

This change does not impact fit, form, function or reliability of the products.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_19_0091_Rev_-_Qualification Results Summary for the HMC487 LFCSP Part.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	**Europe:**	**Japan:**	**Rest of Asia:**
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (2)				
HMC487 / HMC487LP5E	HMC487 / HMC487LP5ETR			

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	16-May-2019	16-May-2019	Initial Release.

Moisture Sensitivity Level Rating Change for HMC487

Qualification Results Summary

MSL-3 Rating Change for HMC487 Device.

QUALIFICATION RESULTS			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Solder Heat Resistance (SHR)*	JEDEC/ IPC J-STD-020	60	PASS
Temperature Cycling (TC)*	JEDEC JESD22-A104	175	PASS

*These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.